

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC016N06NS	**Issued**	08. April 2022
MA#	MA005623305		
Package	PG-TDSON-8-17	**Weight***	119.80 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12665	12665
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
	non noble metal	copper	7440-50-8	37.762	31.52	31.56	315214	315625
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	372	372
encapsulation	organic material	carbon black	1333-86-4	0.130	0.11		1088	
	plastics	epoxy resin	-	5.085	4.24		42448	
	inorganic material	silicondioxide	60676-86-0	38.247	31.93	36.28	319269	362805
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12118	12118
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1382	1382
solder	non noble metal	tin	7440-31-5	0.042	0.04		351	
	noble metal	silver	7440-22-4	0.053	0.04		439	
	non noble metal	lead	7439-92-1	2.010	1.68	1.76	16782	17572
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	zinc	7440-66-6	0.026	0.02		221	
	non noble metal	iron	7439-89-6	0.529	0.44		4416	
	non noble metal	copper	7440-50-8	21.482	17.93	18.40	179323	184015
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		112	
	non noble metal	iron	7439-89-6	0.269	0.22		2243	
	non noble metal	copper	7440-50-8	10.909	9.11	9.34	91063	93446
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com